Microsemi
Power and Microelectronics Group (PMG) – Phoenix Division

Product Change Notification

Date: **Tuesday, March 15, 2011**

PCN#: **140A00199**

Subject: **Solder bump alloy change to all Power PC die**

Dear Customer,

In an effort to better communicate to you, our user community, we have implemented a e-mail version for our PCN process in addition to our PCN website. While you may receive a notification from us concerning a particular part or part numbers, it is not an indication that you use or have ordered these particular parts, but merely a communication to notify our user community as a whole. Please review your sales orders, POs, records, etc. to determine if this particular PCN impacts your activities or affects your business.

Microsemi Power and Microelectronics Group wishes to inform you of a change to the Power PC die used in the following products:

WED3C755E8Mx-xxxx, WED3C7410E16MCx-xxxx

The current PPC die used in all our modules is going through a minor change to the flipchip solder alloy. These changes are being imposed by our die supplier. The new module part numbers will be:

WED3C755E8MDx-xxxx, WED3C7410E16MDx-xxxx

Microsemi Power and Microelectronics Group will continue to support the existing military and compliant product until the depletion of the old die revision. Product based on the old die revision will be sold on a "first come first serve" basis. Contact the factory for availability.

As technology moves at a much faster pace, advanced embedded electronic components play a more strategic role. Constant changes and advancements in technology mandate that we anticipate changes and directions in technology for the benefit of our customers. As one of the pioneers in advanced semiconductor packaging and high-density memory solutions, we stand ready to assist you in managing this evolution of echnology. If we can provide any additional assistance, please contact us at 602.437.1520 or complete a contact form at www.whiteedc.com/contact_us.html.

Best regards,
Microsemi Power and Microelectronics Engineering Group